

## High-performance passivated Black Silicon

### KEYWORDS

- Black silicon
- Passivation
- Uniformity
- Scalable

### Technology Market

Anti-reflective micro-structures for optical applications

- ✓ Light trapping for solar cells
- ✓ Optoelectronic applications
- ✓ Sensors

### The UCL invention

Materials for optoelectronic applications and especially for the conversion of light into an electrical signal need to combine two main parameters: (i) to harvest a maximum number of photons out of an incident light and (ii) to recover a sufficient lifetime of the generated minority charge carriers.

In this framework, we developed black silicon (B-Si) structures having cutting-edge opto-electronical properties; such as an extremely low front reflectance ( $R < 0.5\%$ ), thereby enhancing the light absorption (Fig. 1) in combination with a very high minority-carrier (MC) lifetime ( $\tau > 1\text{ms}$  in the solar MCD range, Fig. 2). Such opto-electronic properties are of utmost importance for next-generation high-efficiency PERC and IBC solar cell technologies.

Additionally, the robust process proposed here is **scalable** on industrial size solar-graded wafers (15.6 cm x 15.6 cm) (inserts Fig.1). Moreover, the proposed innovation can replace the standard texturization step in PERC and IBC solar cell processing and is **adaptable** for both monocrystalline and polycrystalline silicon substrates (Fig. 3).

### Key features of the invention

#### Properties

- ✓ Absorbance close to Yablonoitch limit
- ✓ Specular Reflectance  $< 0.5\%$
- ✓ Hemispherical Reflectance  $< 2\%$
- ✓ Angular reflectance ( $\theta = 0^\circ$  up to  $60^\circ$ )  $< 1\%$
- ✓ Minority-carrier lifetime  $> 1\text{ms}$
- ✓ SRV  $< 5\text{ cm/s}$  for p/n-type, FZ, c-Si  $< 100\%$
- ✓ Large scale homogeneity ( $243.36\text{ cm}^2$ )

#### Process

- ✓ Robust process for mono & poly-Si
- ✓ Single step Mask-free process
- ✓ Ultra-thin passivation layers
- ✓ Replacement of the KOH/TMAH steps
- ✓ Metal contamination-free plasma step
- ✓ Work on as-cut rough surfaces
- ✓ In-situ  $2\text{ }\mu\text{m}$  surface silicon removal

### Technology Status

TRL 4 – technology validated in lab

This work is the subject of an EP patent application filed on 20<sup>th</sup> March 2017 (application number EP17161813.5).

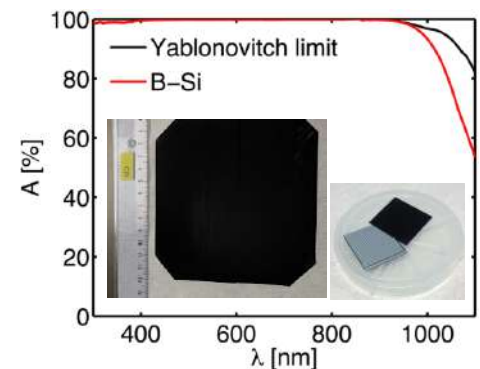


Fig. 1. Absorbance. Insert shows an Industry size solar wafer (left) and IBC solar cells (right) with our B-Si.

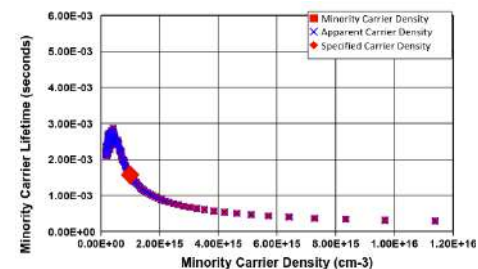


Fig. 2. MC-lifetime versus MCD measured using Sinton WCT-120 lifetime tester in transient photoconductance decay mode (zero instrument is performed prior to the measurements).



Fig. 3. Four wafers with B-Si (left). Comparison between two polycrystalline Si samples before and after B-Si step.

INTERESTED TO DEVELOP AND / OR COMMERCIALISE THIS TECHNOLOGY

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